

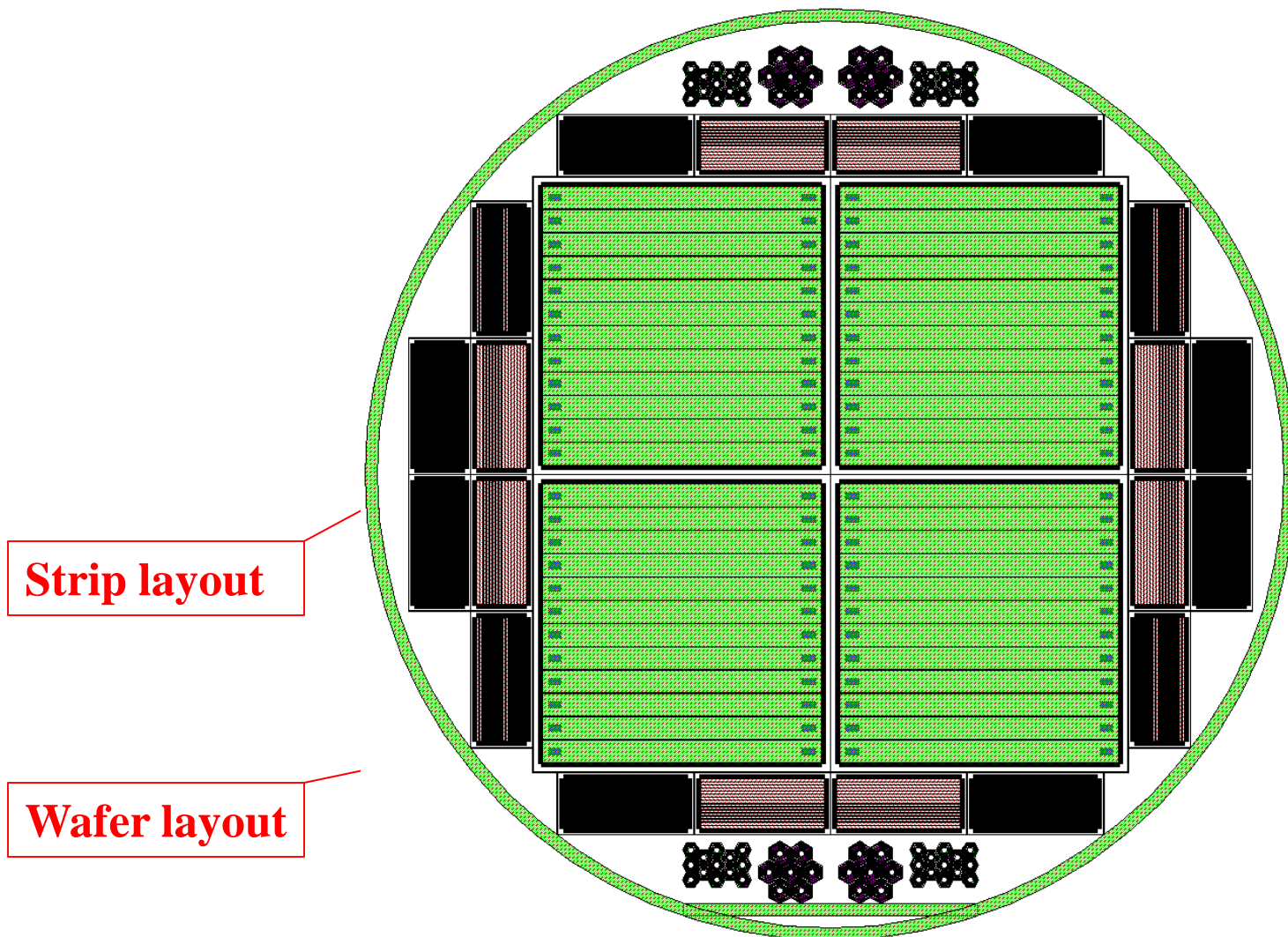
Status@Prague

- → design of sensors for production submission
- → plans for near future

ON Semiconductor

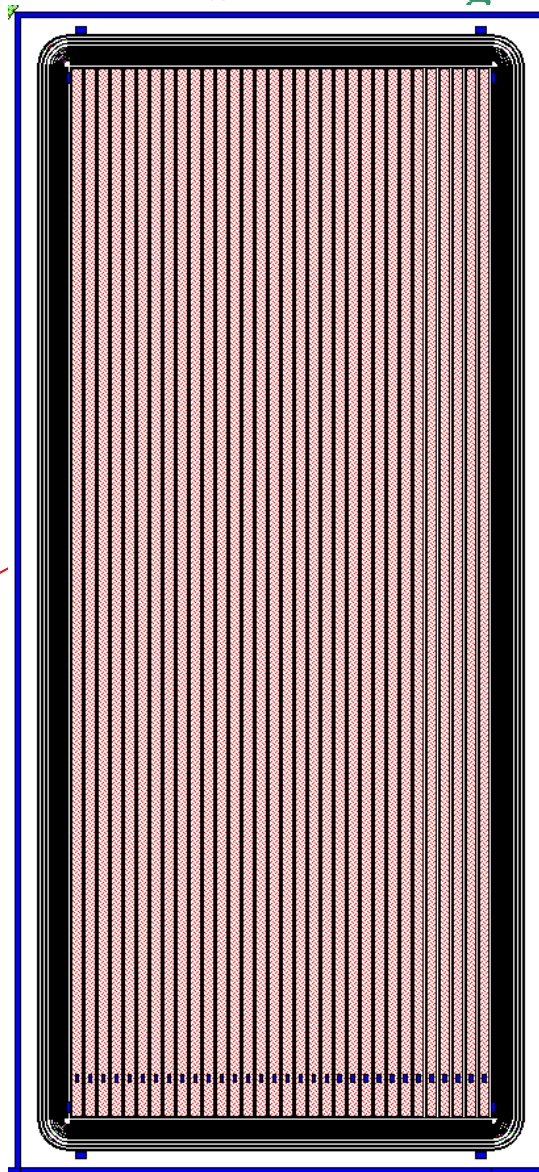
- ON Semiconductor: *6" wafers*
- → stepping mask projection machines,
- → the stitching technique is needed

- „little“ problem with funding – delay
- → problem with purchase 6“ P-type HiRes wafers → big lead time (Topsil) → received just recently



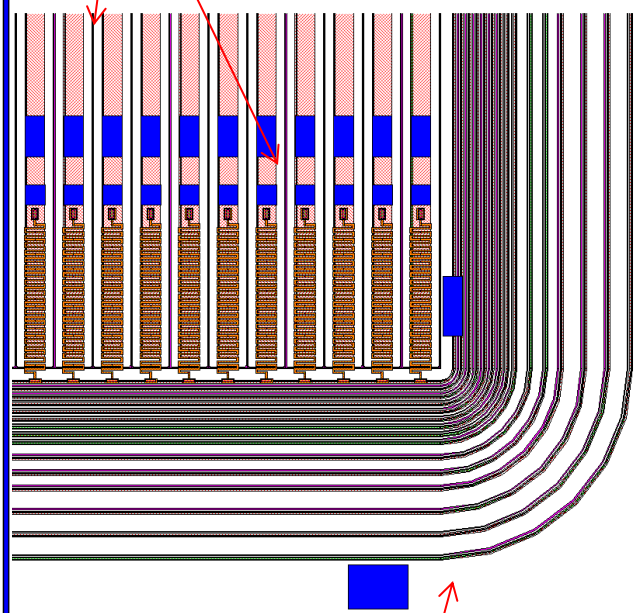
Sensor design

Strip layout



P-stops

Resistor details



Corner details

ON Semiconductor

- Purchase full ingot → big lead time → costly
- → *as a result we have quite good portfolio of wafers 6“: P-type, N-type, 300 micrometers thick.*
- Rushing with design – changing every day!! (not waste time with details)
- **Stitching !! – very urgent task of the day.**

Further steps

- **→ finalization of the layout and prepare production submission**
(end of April / beginning of May)
- **→ prototype → sensor characterization**
(~ summer 2013)

Thank you